PCN Number:	20251105000.1	**PCN Date:**	November 05, 2025
Title:	Qualification of DFAB as an additional Fab site option for select JIBB devices		
Customer Contact:	Change Management Team	**Dept:**	Quality Services
Proposed 1st Ship Date:	February 03, 2026	**Sample requests accepted until:**	January 04, 2026*

***Sample requests received after January 04, 2026 will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of DFAB as an additional Wafer Fab option for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
SFAB	JIBB	150 mm	DFAB	JIBB	200 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
DL-LIN	**DLN**	**USA**	**Dallas**

Sample product shipping label (not actual product label):

Product Affected:

INA125U	INA217AIDWR	OPA445AU/2K5	OPA549S
INA125U/2K5	INA217AIDWT	OPA452FA/500	OPA549T
INA125UA	LOG112AID	OPA452FAKTWT	OPA552FA/500
INA125UA/2K5	LOG112AIDR	OPA453FAKTWT	OPA552FAKTWT
INA143U/2K5	OPA2244EA/2K5	OPA453TA	OPA552UA
INA143UA/2K5	OPA2244UA/2K5	OPA453TA-1	OPA552UA/2K5
INA163UA	OPA244NA/3K	OPA541AP	PGA204AU
INA163UA/2K5	OPA244UA/2K5	OPA541BM	PGA204AU/1K
INA2132U	OPA2541BM	OPA541SM	PGA204BU
INA2132U/2K5	OPA2541SM	OPA547F/500	PGA204BU/1K
INA2132UA	OPA2541SMQ	OPA547FKTWT	PGA205AU
INA2132UA/2K5	OPA2544T	OPA547T	PGA205AU/1K
INA2143U	OPA445AP	OPA547T-1	PGA205BU
INA2143UA	OPA445AU		

For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: INA168QDBVRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	3/2400/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	3/30/0
ESD	E2	ESD CDM	-	1000 Volts	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/6/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device INA168QDBVRQ1 is qualified at MSL1 260C

- Qual Device INA168QDBVRQ1 is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2206-002

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.